

Appl. No. 10/813,409
Amdt. Dated July 9, 2007
Reply to Office Action of April 10, 2007

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Amendments to the Specification

Please replace paragraph [0012] with the following amended paragraph:

[0012] In the first step, the resin substrate 30 is formed using a conventional process such as injection molding, extruding, or drawing. The resin may have at least one component selected from the group of polyvinyl chloride, polyethylene terephthalate, acrylonitrile-butadiene-styrene, polycarbonate, polyimide, polyetherimide, polyphenylene sulfide, polysulfone, polystyrene, glycol-modified polyester, polypropylene, and liquid crystal polymers. In this embodiment, the targets 10, 10' and 10'' are respectively a nickel (Ni) target, a copper (Cu) target and a stainless steel target. The targets 10, 10', 10'' are formed using known methods of the art. After the targets 10, 10', 10'' are formed and respectively mounted [[them]] on the cathodes 12, 12' and 12'', then the target modules 1, 1', 1'' are available for magnetron sputtering. At this time, the switches 16, 16' and 16'' are open and the targets 10, 10', 10'' are shielded by target shields (not shown) from being damaged or corroded. The resin substrate 30 is mounted on the support 4, keeping a predetermined distance between the substrate 30 and the targets 10, 10', 10''. The support 4 can move freely along a plane facing the targets 10, 10', 10'' and can be retained in the sputtering area of each target 10, 10', 10''.